

800V Super-Junction Power MOSFET

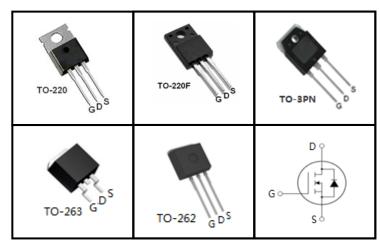
FEATURES

- $\bullet \quad \text{Very low FOM R}_{\text{DS(on)}} \times \text{Q}_{\text{g}} \\$
- 100% avalanche tested
- RoHS compliant

RoHS

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



Device Marking and Package Information						
Device	TPP80R300C	TPA80R300C	TPV80R300C	TPC80R300C	TPB80R300C	
Package	TO-220	TO-220F	TO-3PN	TO-262	TO-263	
Marking	80R300C	80R300C	80R300C	80R300C	80R300C	

Absolute Maximum Ratings $T_C = 25^{\circ}C$, unless otherwise noted						
		Value				
Parameter	Symbol	TO-220, TO-3PN TO-262,TO-263	TO-220F	Unit		
Drain-Source Voltage (V _{GS} = 0V)	V _{DSS}	800		V		
Continuous Drain Current	I _D	, 15		Α		
Pulsed Drain Current (note1)	I _{DM}	45		Α		
Gate-Source Voltage	V _{GSS}	±30		V		
Single Pulse Avalanche Energy (note2)	E _{AS}	480		mJ		
Avalanche Current (note1)	I _{AR}	4		Α		
Repetitive Avalanche Energy (note1)	E _{AR}	0.75		mJ		
Power Dissipation (T _C = 25°C)	P _D	151	34	W		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55~+150		°C		

Thermal Resistance						
		Value				
Parameter	Symbol	TO-220, TO-3PN TO-262,TO-263	TO-220F	Unit		
Thermal Resistance, Junction-to-Case	R _{thJC}	0.83	3.7	•C/W		
Thermal Resistance, Junction-to-Ambient	R _{thJA}	62	80	30/00		

V1.0 www.tsinghuaicwx.com



TPP80R300C, TPA80R300C, TPV80R300C, TPC80R300C, TPB80R300C

Wuxi Unigroup Microelectronics Company

Davamatav	Comet1	Took Countities	Value				
Parameter	Symbol Test Conditions		Min.	Тур.	Max.	Unit	
Static		•		•			
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_D = 250\mu A$	800			V	
Zoro Coto Voltogo Drain Current		$V_{DS} = 800V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 800V, V_{GS} = 0V, T_{J} = 150^{\circ}C$			100	μA	
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 30V$			±100	nA	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.5		4.5	V	
Drain-Source On-Resistance (Note3)	R _{DS(on)}	$V_{GS} = 10V, I_D = 7.5A$		0.26	0.3	Ω	
Forward Transconductance (Note3)	g _{fs}	$V_{DS} = 10V, I_{D} = 7.5A$		18.8		S	
Dynamic					-		
Input Capacitance	C _{iss}			2330		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0V, V_{DS} = 50V,$ f = 1.0MHz		116			
Reverse Transfer Capacitance	C _{rss}			7			
Total Gate Charge	Q_g			46			
Gate-Source Charge	Q_{gs}	$V_{DD} = 640 \text{V}, I_{D} = 15 \text{A}, $ $V_{GS} = 10 \text{V}$		11		nC	
Gate-Drain Charge	Q_{gd}			13			
Turn-on Delay Time	t _{d(on)}			43			
Turn-on Rise Time	t _r	$V_{DD} = 400V, I_{D} = 15A,$		14			
Turn-off Delay Time	t _{d(off)}	$R_G = 25\Omega$		150		ns	
Turn-off Fall Time	t _f			7			
Drain-Source Body Diode Characteris	stics						
Continuous Body Diode Current	Is	T 250C			15	Δ	
Pulsed Diode Forward Current	I _{SM}	T _C = 25°C			45	Α	
Body Diode Voltage	V _{SD}	$T_J = 25^{\circ}\text{C}, I_{SD} = 15\text{A}, V_{GS} = 0\text{V}$		0.9	1.2	V	
Reverse Recovery Time	t _{rr}			460		ns	
Reverse Recovery Charge	Q _{rr}	$V_R = 400V, I_F = I_S,$ $di_F/dt = 100A/\mu s$		3.8		μC	
Peak Reverse Recovery Current	I _{rrm}			35		Α	

Notes

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2. I_{AS} = 4A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 1%

Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

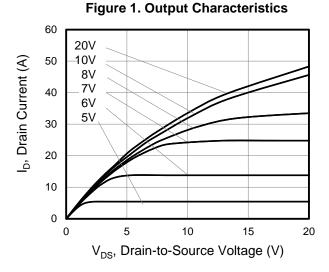


Figure 3. On-Resistance vs. Drain Current

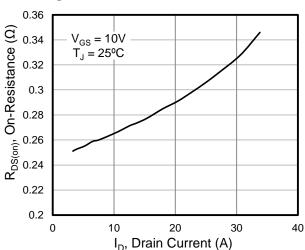


Figure 5. Gate Charge 12 V_{GS}, Gate-to-Source Voltage (V) 10 $V_{DD} = 120V$ 8 6 $V_{DD} = 640V$ 4 2 0 0 10 20 50 Q_a, Total Gate Charge (nC)

Figure 2. Transfer Characteristics

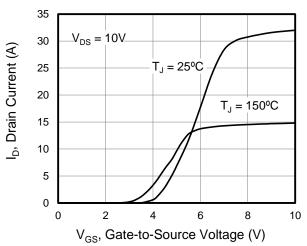


Figure 4. Capacitance

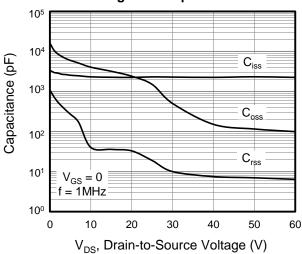


Figure 6. Body Diode Forward Voltage

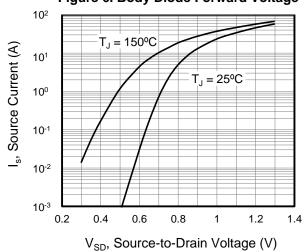




Figure 8. Threshold Voltage vs.

Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Figure 7. On-Resistance vs. **Junction Temperature** 3 $V_{GS} = 10V$ 2.5 $I_{D} = 7.5A$ R_{DS(on)}, (Normalized) 2 1.5 1 0.5 0 50 -100 100 150 200 T_J, Junction Temperature (°C)

Junction Temperature 0.6 $I_{D} = 250 \mu A$ 0.4 0.2 V_{GS(th)}, (Variance) 0 -0.2 -0.4 -0.6 -0.8 -1 -1.2 -100 -50 100 150 200 T_J, Junction Temperature (°C)

Figure 9. Transient Thermal Impedance TO-220,TO-262,TO-263,TO-3PN **10**0 Z_{thJC}, Thermal Impedance (K/W) 10-1 D = 0.510-2 D = 0.2D = 0.1D = 0.0510-3 D = 0.02D = 0.01Single Pulse 10-4 10⁻⁷ 10-6 10-1 T_p, Pulse Width (s)

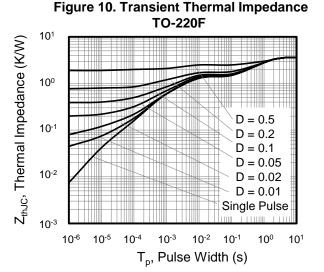




Figure A: Gate Charge Test Circuit and Waveform

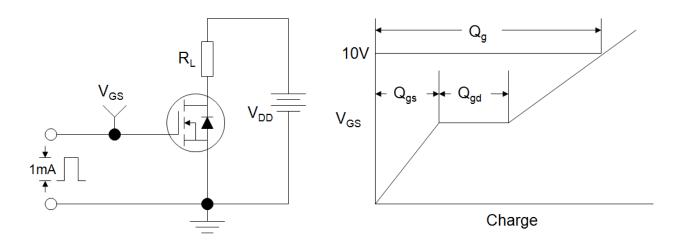


Figure B: Resistive Switching Test Circuit and Waveform

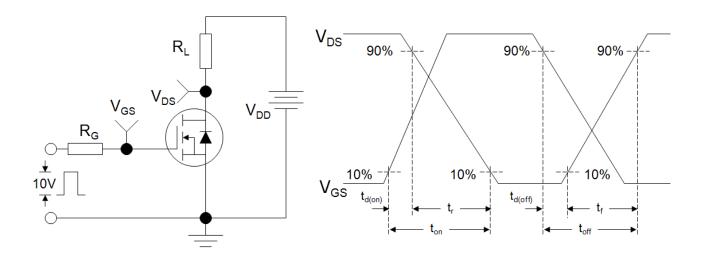
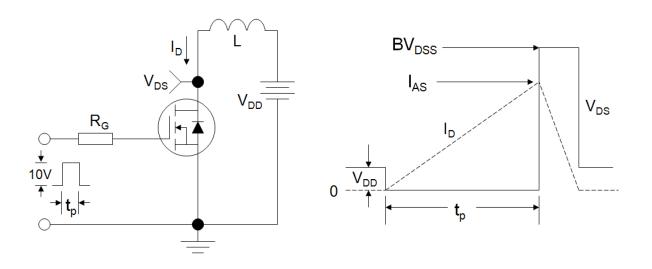


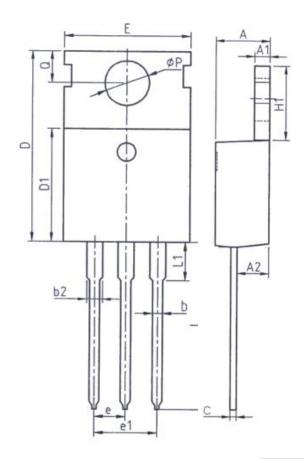
Figure C: Unclamped Inductive Switching Test Circuit and Waveform

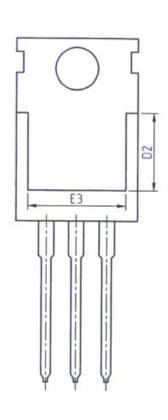


V1.0 5 www.tsinghuaicwx.com



TO-220



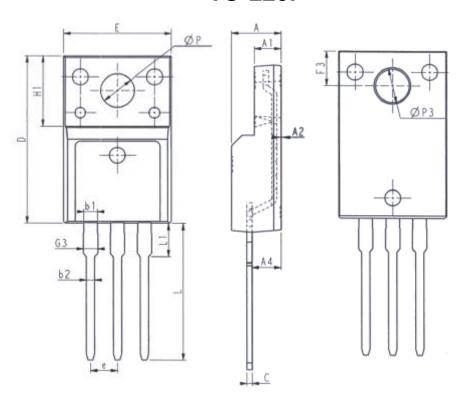


Unit: mm					
Symbol	Min.	Max.			
Α	4. 37	4. 77			
A1	1. 25	1. 45			
A2	2. 20	2. 60			
b	0. 70	0. 95			
b2	1. 17	1. 47			
С	0. 40	0. 65			
D	15. 10	16. 10			
D1	8. 80	9. 40			
D2	5. 50	_			

Unit: mm					
Symbol	Min. Max.				
E	9. 70	10.30			
E3	7. 00	-			
е	2. 54BSC				
e1	5. 08BSC				
H1	6. 25 6. 85				
L	12. 75	13.80			
L1	-	3. 40			
P	3. 40	3. 80			
Q	2. 60	3. 00			



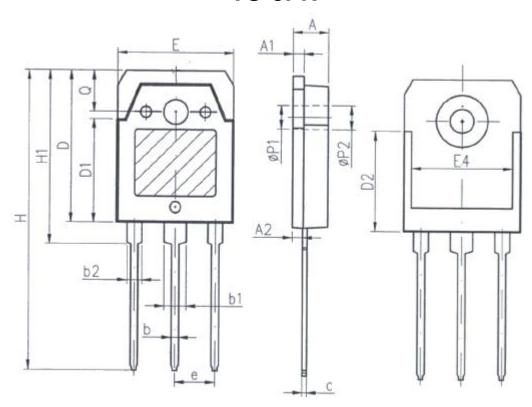




l	Unit: mm			Jnit: mm	1
Symbol	Min.	Max.	Symbol	Min.	Max.
E	9. 96	10.36	L	12. 68	13. 28
Α	4. 50	4. 90	L1	2. 93	3. 13
A1	2. 34	2. 74	Р	3. 03	3. 38
A2	0.30	0.60	Р3	3. 15	3. 65
A4	2. 56	2. 96	F3	3. 15	3. 45
С	0.40	0. 65	G3	1. 25	1. 55
D	15. 57	16. 17	b1	1. 18	1. 43
H1	6. 70	OREF	b2	0. 70	0. 95
е	2. 54	4BSC			

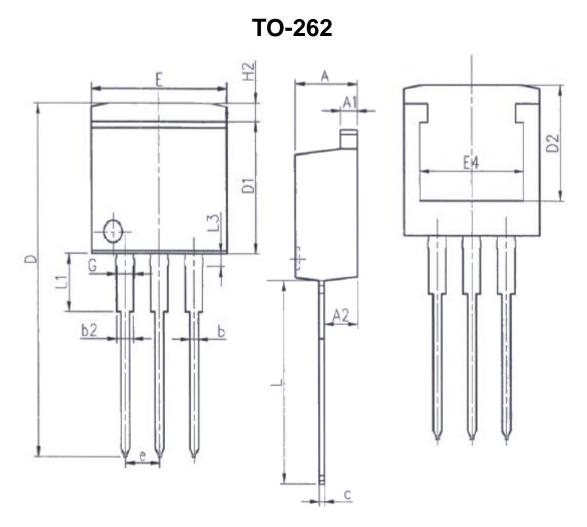


TO-3PN



Unit:mm				
Symbol	Symbol Min.			
Α	4. 6	Max. 5		
A1	1. 4	1. 65		
A2	1. 18	1. 58		
b	0.8	1. 2		
b1	2. 8	3. 2		
b2	1. 8	2. 2		
С	0. 5	0. 75		
D	19. 6	20. 2		
D1	13. 55	14. 25		
D2	12. 9	9REF		
E	15. 35	15. 85		
E4	12. 6	-		
e	5. 45TYP			
Н	40. 1	40. 9		
H1	23. 15	23. 65		
P1	3. 2REF			
P2	3. 5REF			



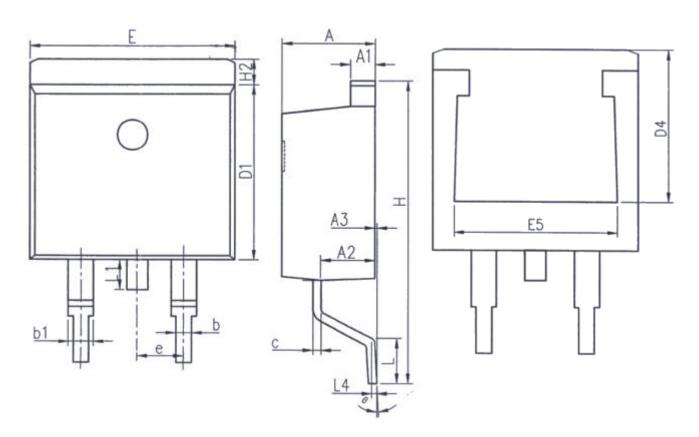


Unit: mm					
Symbol	Min.	Max.			
Α	4. 37	4. 77			
A1	1. 22	1. 42			
A2	2. 47	2. 87			
b	0. 70	0. 97			
b2	1. 17	1. 42			
С	0. 28	0.53			
D	23. 20	24. 02			
D1	8. 38	8. 90			
D2	6. 00	_			

Unit: mm					
Symbol	Min.	Max.			
E	9. 90	10. 39			
E4	7. 30	_			
е	2. 54	4BSC			
G	1. 25	1.50			
H2	-	1. 31			
L	13. 34	14. 10			
L1	3. 30	4. 06			
L3	0. 95	1. 15			



TO-263



Unit: mm					
Symbol	Min.	Max.			
Α	4. 37	4. 77			
A 1	1. 22	1. 42			
A2	2. 49	2. 89			
A3	0. 00	0. 25			
b	0. 70	0. 96			
b1	1. 17	1. 47			
С	0. 30	0. 53			
D1	8. 50	8. 90			
D4	6. 60	_			

Unit: mm					
Symbol	Min.	Max.			
E	9.86	10.36			
E 5	7. 06	-			
е	2. 54BSC				
Н	14. 70	15. 50			
H2	1. 07	1. 47			
L	2.00	2. 60			
L1	1. 40	1. 70			
L4	0. 25	5BSC			
θ	0°	9°			

TPP80R300C, TPA80R300C, TPV80R300C, TPC80R300C, TPB80R300C



Wuxi Unigroup Microelectronics Company

Disclaimer

All product specifications and data are subject to change without notice.

For documents and material available from this datasheet, Wuxi Unigroup does not warrant or assume any legal liability or responsibility for the accuracy, completeness of any product or technology disclosed hereunder.

No license, express or implied, by estoppels or otherwise, to any intellectual property rights is granted by this document or by any conduct of Wuxi Unigroup.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling Wuxi Unigroup products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Wuxi Unigroup for any damages arising or resulting from such use or sale.

Wuxi Unigroup disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Wuxi Unigroup's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

Wuxi Unigroup Microelectronics CO., LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

In the event that any or all Wuxi Unigroup products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

Information (including circuit diagrams and circuit parameters) herein is for example only. It is not guaranteed for volume production. Wuxi Unigroup believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

V1.0 www.tsinghuaicwx.com